

Sumikon® EME-7720S

Epoxy; Epoxide
Sumitomo Bakelite Co., Ltd.

Message:
Sumikon 7700-Series compounds are multi-functional-type molding compounds developed for overmolded BGA packages.

General Information			
UL YellowCard	E41429-232561		
Features	Low hygroscopicity		
Uses	Semiconductor molding compound		
Forms	Liquid		
Processing Method	Enclosure		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.97	g/cm ³	ASTM D792
Water Absorption (24 hr)	0.32	%	ASTM D570
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus (25°C)	19600	MPa	ASTM D790
Flexural Strength (25°C)	147	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	190	°C	ASTM E1356
Thermal Conductivity	0.79	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	1.0E+13	ohms·cm	ASTM D257
Thermoset	Nominal Value	Unit	
Demold Time (175°C)	0.50 - 1.7	min	
Post Cure Time (175°C)	2.0 - 8.0	hr	
Additional Information			

Spiral Flow, SB-U-03-003: 90 cmGel Time, SB-U-03-005, 175°C: 30 secThermal Expansion, SB-U-02-002, TTg: 4.1 E-5/°CFlexural Strength, SB-U-01-001, 240°C: 39.2 MPaFlexural Modulus, SB-U-01-002, 240°C: 2158 MPaUL-94 Flame Class, SB-U-03-003: V-0Extracted Na+, SB-U-04-043: <1 ppmExtracted Cl-, SB-U-04-043: 5 ppmTransfer Pressure: 687-1177 MPa

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